

MA2SD29

Silicon epitaxial planar type

For super high speed switching

■ Features

- Low forward voltage: $V_F < 0.42$ V (at $I_F = 100$ mA)
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr} .

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Forward current (Average)	$I_{F(AV)}$	100	mA
Peak forward current	I_{FM}	200	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

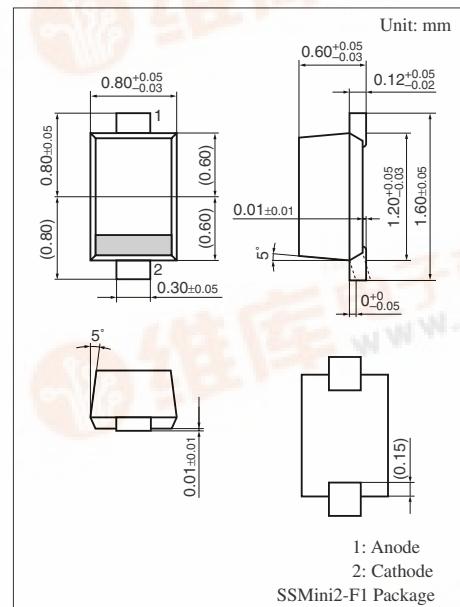
Note) * : The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current	I_{R1}	$V_R = 10$ V			25	μA
	I_{R2}	$V_R = 30$ V			120	
Forward voltage	V_{F1}	$I_F = 10$ mA		0.25	0.29	V
	V_{F2}	$I_F = 100$ mA		0.39	0.42	
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		11		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100$ mA $I_{rr} = 10$ mA, $R_L = 100$ Ω		1		ns

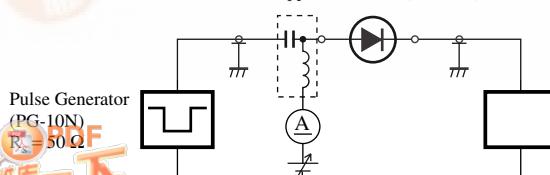
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 250 MHz
4. *: t_{rr} measurement circuit



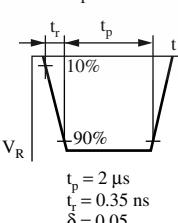
Marking Symbol: 8M

Bias Application Unit (N-50BU)

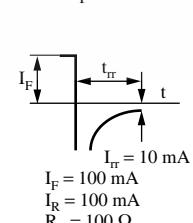


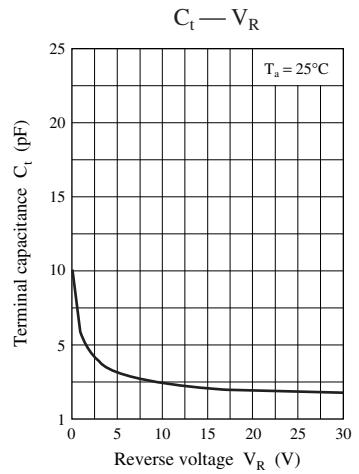
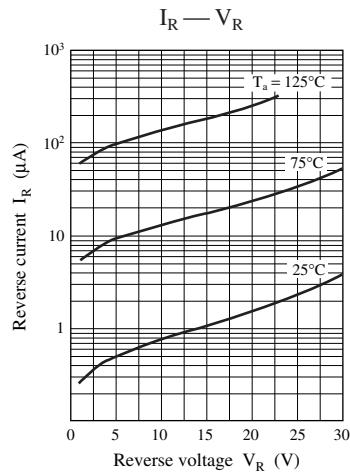
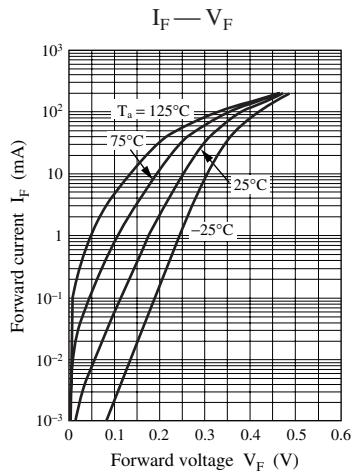
Wave Form
Analyzer
(SAS-8130)
 $R_i = 50$ Ω

Input Pulse



Output Pulse





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